

### **REMARKS/ARGUMENTS**

Claims 43 and 103-105 are amended to correct a typographical error but not for reasons of patentability. Claims 43, 48, 49, 51-57, 59-65, 74-81, and 93-109 remain pending in the application. Applicants respectfully request reexamination and reconsideration of the application.

Claims 43, 48, 49, 51-57, 59-65, 74-81, and 93-109 were rejected on the grounds of non-statutory obvious-type double patenting in view of claims 27 and 35 is US Patent No. 5,974,662. In response, Applicants submit a Terminal Disclaimer, which should overcome the rejection.

To ensure that the rejection in the Office Action of March 6, 2007 of claim 43 as anticipated by US Patent No. 5,539,324 to Wood and Corbett ("Wood") has been properly addressed, Applicants assert that Wood does not enable the statement that "[t]he contact tips are planar so that contact of each die pad occurs simultaneously" (Wood col. 4, lines 19-20). Applicants submit that it is not possible to manufacture a contact structure with contact tips 31 so aligned that each contact tip 31 contacts each pad of dies on a wafer 30 simultaneously. Certainly, Wood does not teach how to make contact tips 31 so aligned. Nor does Wood teach or hint at a mechanism for adjusting a planar orientation of the contact tips 31 to correspond to a planar orientation of the pads of the dies of wafer 30. Wood thus does not provide enough information for a person of ordinary skill in the field to make and use an apparatus in which the contact tips 31 are so planar that the contact tips 31 contact pads of the dies of wafer 30 simultaneously. Wood cannot therefore be relied on to reject claim 43. (See MPEP 2121.01.) For at least this reason, claim 43 is patentable over Wood.

Moreover, Wood's statement at column 4, lines 19-20 that "[t]he contact tips are planar so that contact to each die pad occurs simultaneously" appears to be contradicted by Wood's description at column 6, lines 8-18, which implies that contact tips 31 need be only sufficiently planar with respect to the die pads on wafer 30 so that all of the contact tips 31 contact all of the die pads of wafer 30. Thus, reading Wood's disclosure as a whole, Wood teaches nothing more than that contact tips 31 should be sufficiently planar so that all of contact tips 31 contact all of the pads of the dies of wafer 30, which is no better than the state of the art in the field prior to Applicants' disclosure. For this additional reason, Wood does not anticipate claim 43.

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Applicants submit that all of the claims are allowable and the application is in condition for allowance. If at any time the Examiner believes that a discussion with Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned at (801) 426-2106.

Respectfully submitted,

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